



Global Business Council

Addressing the business side of microelectronics

Spring 2007 Conference Program

March 18 & 19, 2007
Doubletree Paradise Valley Resort
Scottsdale, AZ

Sunday, March 18, 2007

12:00 Noon – GBC Golf Tournament

3:00 PM – Registration Opens

6:00 PM – Welcome Reception

Monday, March 19, 2007

7:00 AM – Registration Opens

7:30 AM – Continental Breakfast

8:00 AM – Opening Remarks

Laurie Roth, GBC Co-Chair

Please register at
www.imap.org/gbc

8:15 AM - State-of-the-art Technology Integration Trends and 3-D Wafer-Level Integration - Brandon Prior, Prismark Partners

9:00 AM - iNEMI Roadmaps – A Blueprint for Industry Collaboration - Chuck Richardson, iNEMI

9:45 AM - Break

10:15 AM - DuPont's Advanced Materials Pipeline for the Device Packaging Industry - Phil Thomas, Global Technology, DuPont Electronic Technologies

11:00AM - Application Specific Packaging Trends and Business Implications, Lee Smith, Amkor Technologies,

12:00 Noon - 1 PM - Lunch

1:00 PM - Semiconductor Industry Update
Brian Matas, Vice President, IC Insights

1:45 PM - RF Devices - Mike Shields, Consultant

2:30 PM - Automotive Electronics: Do you have any business being there? -
Randy Frank, Randy Frank & Associates
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3:15 PM Break

3:45 - Current and Future Microelectronics Packaging for Implantable Medical Devices" - Peter C. Tortorici, Ph.D., Medtronic Microelectronics Center

4:30 - Closing Remarks & Adjourn

All GBC attendees are cordially invited to the Device Packaging Conference Welcome Reception.